SCLS478A - APRIL 2003 - REVISED JANUARY 2004

- **Controlled Baseline** - One Assembly/Test Site, One Fabrication Site
- **Extended Temperature Performance of Up** To -55°C to 125°C
- **Enhanced Diminishing Manufacturing** Sources (DMS) Support
- **Enhanced Product-Change Notification**
- **Qualification Pedigree[†]**
- 2-V to 6-V V_{CC} Operation

[†] Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

description/ordering information

- **Outputs Can Drive Up To 10 LSTTL Loads**
- Low Power Consumption, 20-µA Max ICC
- Typical t_{pd} = 8 ns
- ±4-mA Output Drive at 5 V
- Low Input Current of 1 µA Max

DO	D OR PW PACKAGE (TOP VIEW)										
1Y [1A [1B [2Y [2A [2 3	Ο	14 13 12 11 10] V _{CC}] 4Y] 4B] 4A] 3Y							
2B [GND [6 7		9 8] 3B] 3A							

The SN74HC02 contains four independent 2-input NOR gates. It performs the Boolean function $Y = \overline{A + B}$ or $Y = \overline{A} \bullet \overline{B}$ in positive logic.

TA	PACKA	3E‡	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	TSSOP – PW	Tape and reel	SN74HC02QPWREP	SHC02EP
–55°C to 125°C	SOIC – D	Tape and reel	SN74HC02MDREP	HC02MEP

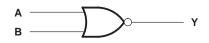
ORDERING INFORMATION

[‡] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE	
(each gate)	

INP	UTS	OUTPUT
Α	В	Y
Н	Х	L
Х	Н	L
L	L	Н

logic diagram (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	
Output clamp current, I_{OK} (V _O < 0 or V _O > V _{CC}) (see Note 1)	
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$	±25 mA
Continuous current through V _{CC} or GND	±50 mA
Package thermal impedance, θ_{JA} (see Note 2): D package	
PW package	113°C/W
Storage temperature range, T _{stg}	. −65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			MIN	NOM	MAX	UNIT
VCC	Supply voltage		2	5	6	V
		V _{CC} = 2 V	1.5			
۷IH	High-level input voltage	V _{CC} = 4.5 V	3.15			V
		V _{CC} = 6 V	4.2			
		V _{CC} = 2 V			0.5	
VIL	Low-level input voltage	$V_{CC} = 4.5 V$			1.35	V
		VCC = 6 V			1.8	
VI	Input voltage		0		VCC	V
VO	Output voltage		0		VCC	V
		V _{CC} = 2 V			1000	
$\Delta t / \Delta v$	Input transition rise/fall time	V _{CC} = 4.5 V			500	ns
		V _{CC} = 6 V			400	
т.	Operating free air temperature	Q-suffix device	-40		125	°C
Τ _Α	Operating free-air temperature	-55		125	C	

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				Т	A = 25°C	;			
PARAMETER	TEST CONDITI	ONS	VCC	MIN	TYP	MAX	MIN	MAX	UNIT
			2 V	1.9	1.998		1.9		
		l _{OH} = -20 μA	4.5 V	4.4	4.499		4.4		
VOH	$V_I = V_{IH} \text{ or } V_{IL}$		6 V	5.9	5.999		5.9		V
		I _{OH} = -4 mA	4.5 V	3.98	4.3		3.7		
		I _{OH} = -5.2 mA	6 V	5.48	5.8		5.2		
			2 V		0.002	0.1		0.1	
		l _{OL} = 20 μA	4.5 V		0.001	0.1		0.1	
VOL			6 V		0.001	0.1		0.1	V
		$I_{OL} = 4 \text{ mA}$	4.5 V		0.17	0.26		0.4	
		I _{OL} = 5.2 mA	6 V		0.15	0.26		0.4	
lı	$V_{I} = V_{CC} \text{ or } 0$		6 V		±0.1	±100		±1000	nA
ICC	$V_{I} = V_{CC} \text{ or } 0,$	IO = 0	6 V			2		40	μA
Ci			2 V to 6 V		3	10		10	pF

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

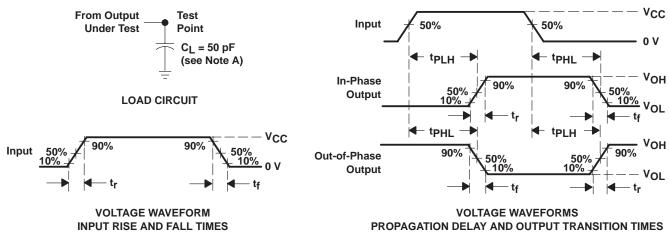
DADAMETED	FROM	то	v	T,	ς = 25°C	;	MINI	MAY	
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN	MAX	UNIT
			2 V		45	90		135	
^t pd	A or B	· · –	4.5 V		9	18		27	ns
			6	6 V		8	15		23
			2 V		38	75		110	
tt		Y	4.5 V		8	15		22	ns
			6 V		6	13		19	

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per gate	No load	22	pF



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_Q = 50 Ω , t_f = 6 ns, t_f = 6 ns.
- C. The outputs are measured one at a time with one input transition per measurement.
- D. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins P	ackage Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74HC02QPWREP	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/04687-02YE	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. **TBD:** The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN74HC02-EP :

- Catalog: SN74HC02
- Automotive: SN74HC02-Q1
- Military: SN54HC02

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Military QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal	
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Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC02QPWREP	TSSOP	PW	14	2000	330.0	12.4	7.0	5.6	1.6	8.0	12.0	Q1



PACKAGE MATERIALS INFORMATION

5-Aug-2008



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC02QPWREP	TSSOP	PW	14	2000	346.0	346.0	29.0

MECHANICAL DATA

MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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